GC2M0160120D
Silicon Carbide Power MOSFET
N-Channel Enhancement Mode

Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Avalanche Ruggedness
- Resistant to Latch-Up
- Halogen Free, RoHS Compliant

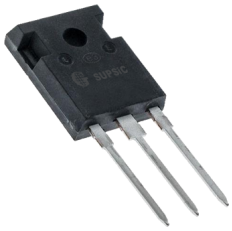
Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

Applications

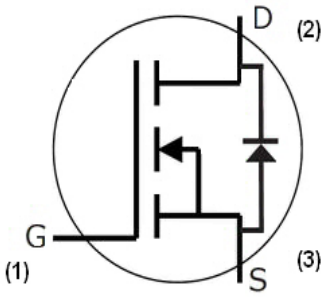
- Solar Inverters
- Switch Mode Power Supplies
- High Voltage DC/DC Converters
- LED Lighting Power Supplies

V_{DS}	1200 V
$I_{D\ @\ 25°C}$	18 A
$R_{DS(on)}$	160 mΩ



TO-247-3

Package



Part Number	Package	Marking
GC2M0160120D	TO-247-3	GC2M0160120

Maximum Ratings (T_C = 25 ˚C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{DSmax}	Drain - Source Voltage	1200	V	V_{GS} = 0 V, I_D = 100 µA	
V_{GSmax}	Gate - Source Voltage	-10/+25	V	Absolute maximum values	
V_{GSop}	Gate - Source Voltage	-5/+20	V	Recommended operational values	
I_D	Continuous Drain Current	18	A	V_{GS} = 20 V, T_C = 25˚C	Fig. 19
		12		V_{GS} = 20 V, T_C = 100˚C	
$I_{D(pulse)}$	Pulsed Drain Current	40	A	Pulse width t_P limited by T_{jmax}	Fig. 22
P_D	Power Dissipation	125	W	T_C=25˚C , T_J = 150 ˚C	Fig. 20
T_J , T_{stg}	Operating Junction and Storage Temperature	-55 to +150	˚C		
T_L	Solder Temperature	260	˚C	1.6mm (0.063”) from case for 10s	
M_d	Mounting Torque	1 8.8	Nm lbf-in	M3 or 6-32 screw	

Electrical Characteristics (T_C = 25˚C unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200			V	V_{GS} = 0 V, I_D = 100 µA	
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.9	4	V	V_{DS} = V_{GS}, I_{DS} = 2.5 mA	Fig. 11
			2.4		V	V_{DS} = V_{GS}, I_{DS} = 2.5 mA, T_J = 150ºC	
I_{DSS}	Zero Gate Voltage Drain Current		1	100	µA	V_{DS} = 1200 V, V_{GS} = 0 V	
I_{GSS}	Gate-Source Leakage Current			250	nA	V_{GS} = 20 V, V_{DS} = 0 V	
$R_{DS(on)}$	Drain-Source On-State Resistance		160	196	mΩ	V_{GS} = 20 V, I_D = 10 A	Fig. 4, 5, 6
			290			V_{GS} = 20 V, I_D = 10A, T_J = 150ºC	
g_{fs}	Transconductance		3.8		S	V_{DS}= 20 V, I_{DS}= 10 A	Fig. 7
			5.3			V_{DS}= 20 V, I_{DS}= 10 A, T_J = 150ºC	
C_{iss}	Input Capacitance		606		pF	V_{GS} = 0 V V_{DS} = 1000 V f = 1 MHz V_{AC} = 25 mV	Fig. 17, 18
C_{oss}	Output Capacitance		55				
C_{rss}	Reverse Transfer Capacitance		5				
E_{oss}	C_{oss} Stored Energy		28		µJ		Fig. 16
E_{AS}	Avalanche Energy, Single Pluse		600		mJ	I_D = 10A, V_{DD} = 50V	Fig. 29
E_{ON}	Turn-On Switching Energy		121		µJ	V_{DS} = 800 V, V_{GS} = -5/20 V, I_D = 10A, $R_{G(ext)}$ = 2.5Ω, L= 434µH	Fig. 25
E_{OFF}	Turn Off Switching Energy		48				
$t_{d(on)}$	Turn-On Delay Time		7		ns	V_{DD} = 800 V, V_{GS} = -5/20 V I_D = 10 A $R_{G(ext)}$ = 2.5 Ω, R_L = 80 Ω Timing relative to V_{DS} Per IEC60747-8-4 pg 83	Fig. 27
t_r	Rise Time		9				
$t_{d(off)}$	Turn-Off Delay Time		13				
t_f	Fall Time		14				
$R_{G(int)}$	Internal Gate Resistance		6.5		Ω	f = 1 MHz, V_{AC} = 25 mV	
Q_{gs}	Gate to Source Charge		11		nC	V_{DS} = 800 V, V_{GS} = -5/20 V I_D = 10 A Per IEC60747-8-4 pg 21	Fig. 12
Q_{gd}	Gate to Drain Charge		17				
Q_g	Total Gate Charge		40				

Reverse Diode Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	3.9		V	V_{GS} = -5 V, I_F=5 A	Fig. 8,9, 10
		3.5			V_{GS} = -5V, I_F=5 A, T_J = 150 °C	
I_S	Continuous Diode Forward Current		25	A	T_C = 25˚C	Note 1
t_{rr}	Reverse Recovery Time	20		ns	V_{GS} = - 5 V, I_{SD} = 10 A, V_R = 800 V dif/dt = 2400 A/µs	Note 1
Q_{rr}	Reverse Recovery Charge	192		nC		
I_{rrm}	Peak Reverse Recovery Current	16		A		

Note (1): When using SiC Body Diode the maximum recommended V_{GS} = -5V

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.9	1.0	K/W		Fig. 21
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient		40			

Typical Performance

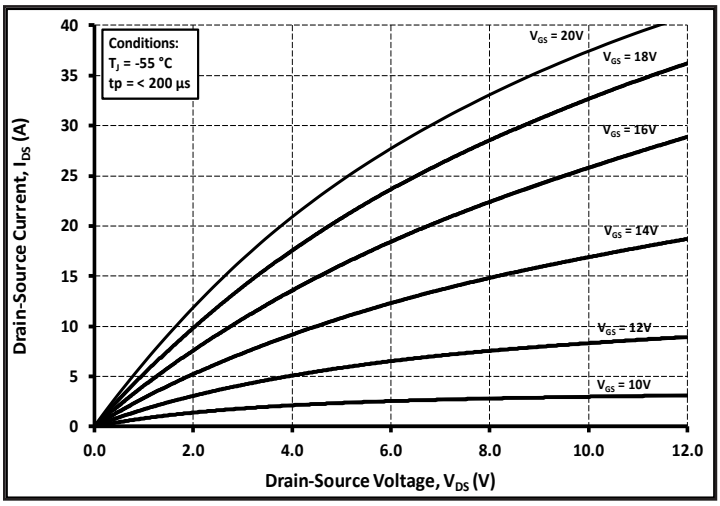


Figure 1. Output Characteristics T_J = -55 °C

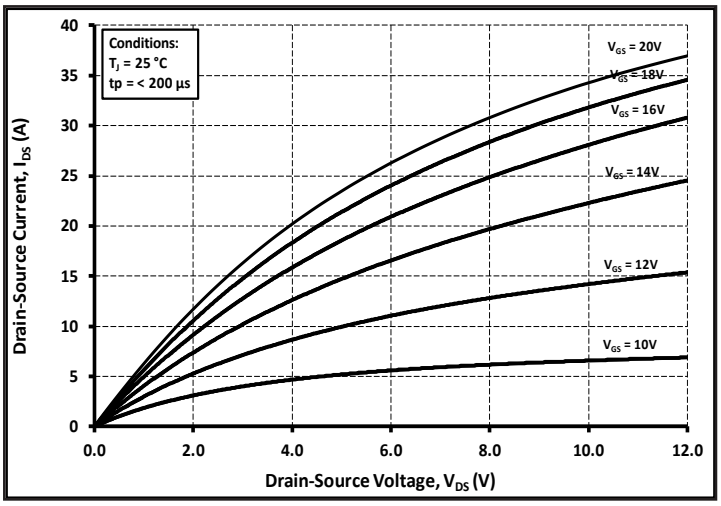


Figure 2. Output Characteristics T_J = 25 °C

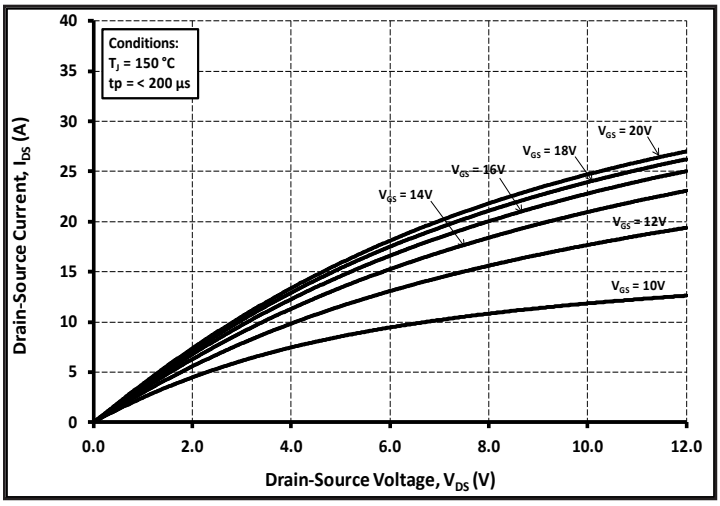


Figure 3. Output Characteristics T_J = 150 °C

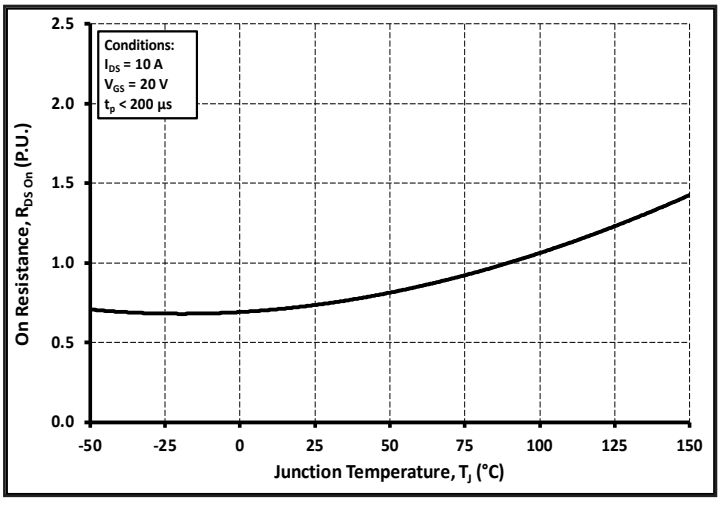


Figure 4. Normalized On-Resistance vs. Temperature

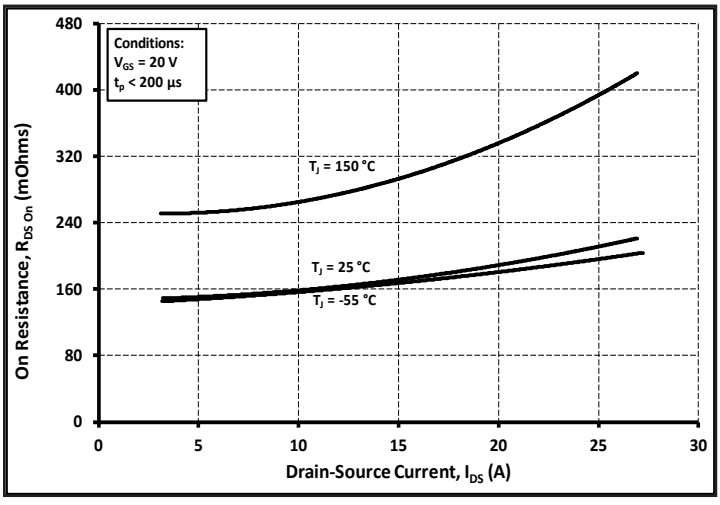


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

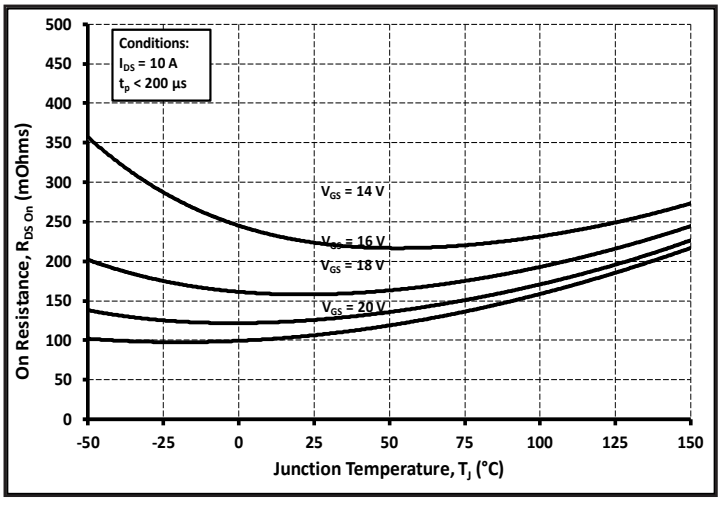


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

Typical Performance

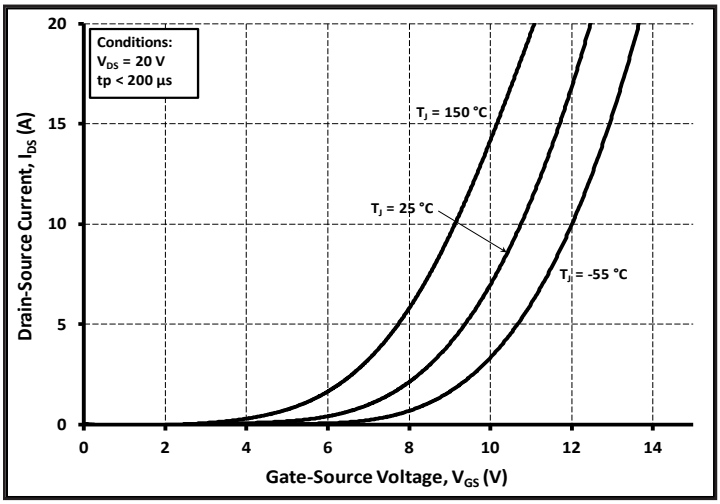


Figure 7. Transfer Characteristic for Various Junction Temperatures

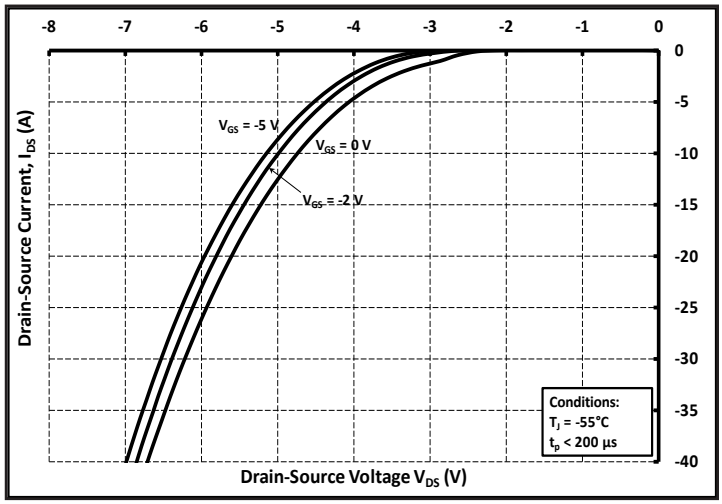


Figure 8. Body Diode Characteristic at -55 ºC

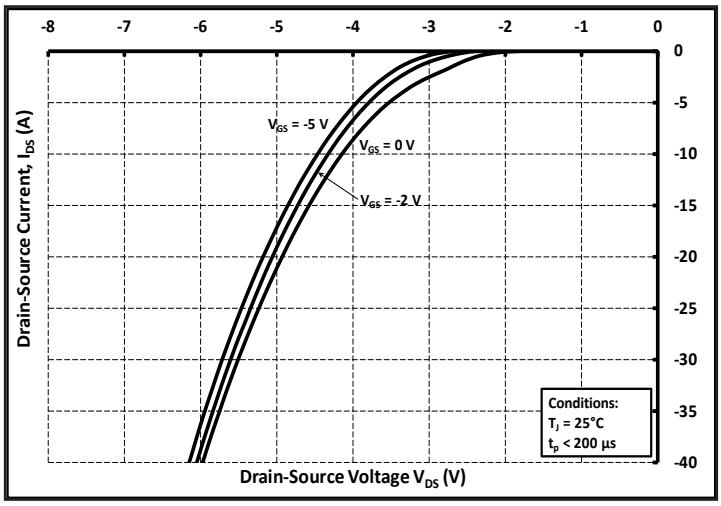


Figure 9. Body Diode Characteristic at 25 ºC

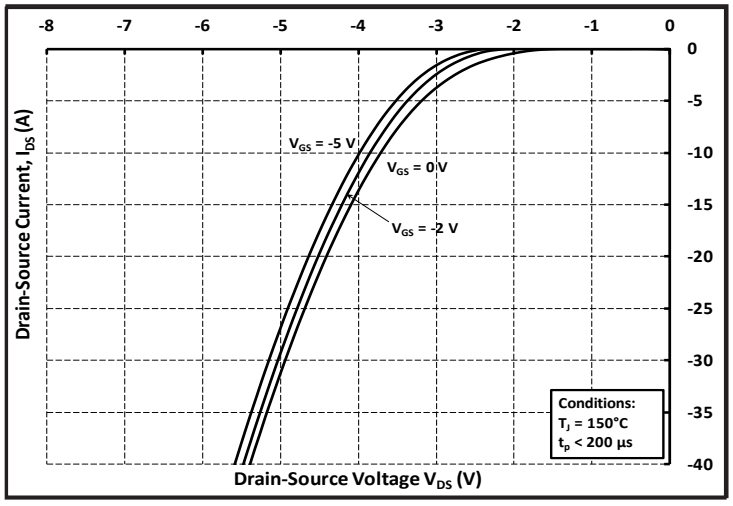


Figure 10. Body Diode Characteristic at 150 ºC

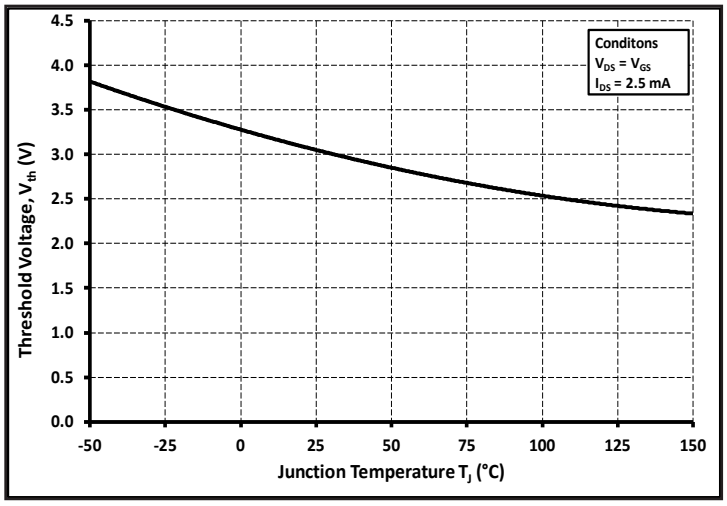


Figure 11. Threshold Voltage vs. Temperature

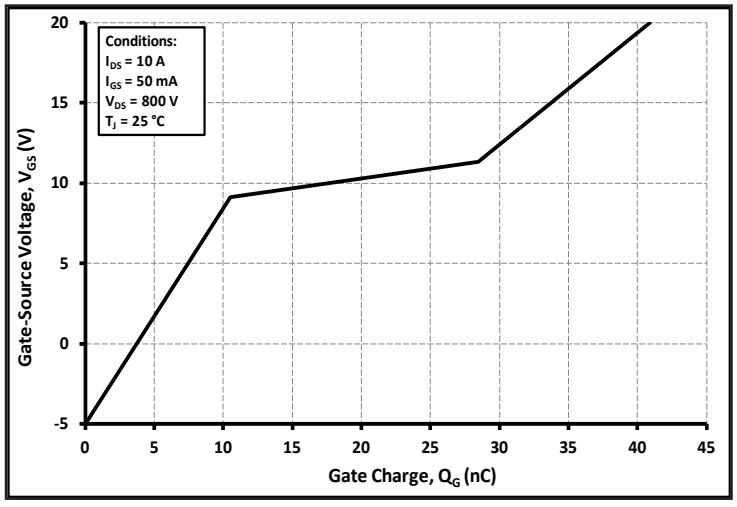


Figure 12. Gate Charge Characteristics

Typical Performance

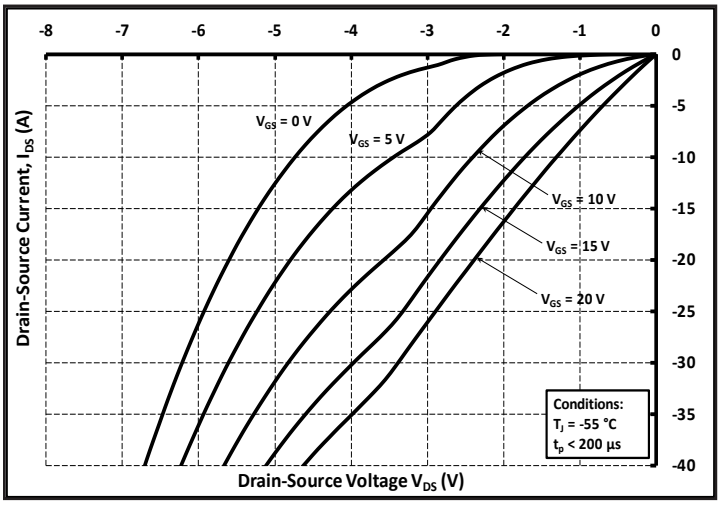


Figure 13. 3rd Quadrant Characteristic at -55 °C

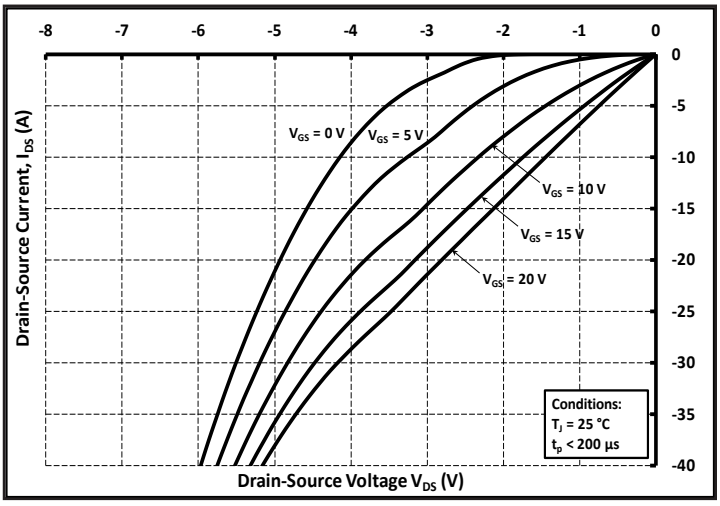


Figure 14. 3rd Quadrant Characteristic at 25 °C

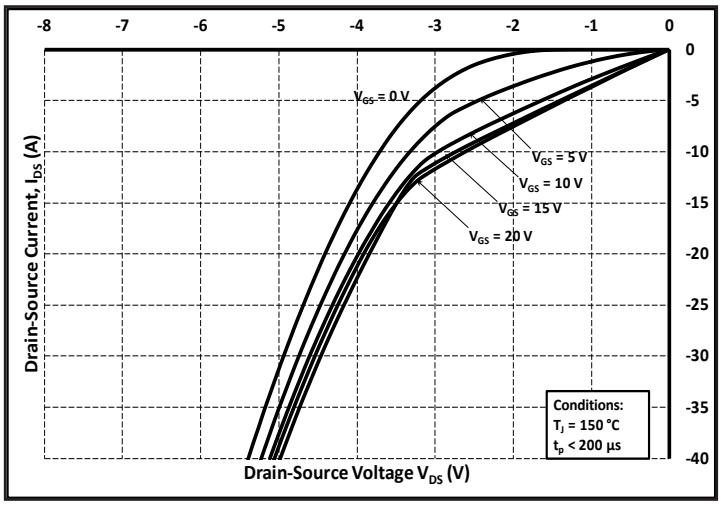


Figure 15. 3rd Quadrant Characteristic at 150 °C

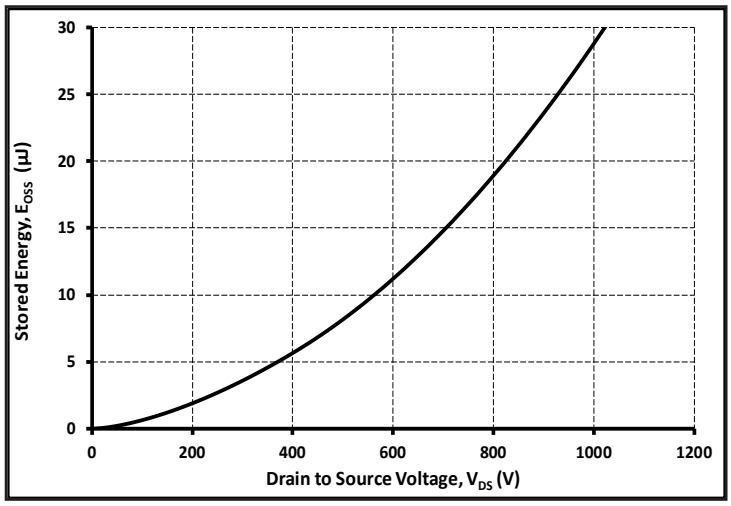


Figure 16. Output Capacitor Stored Energy

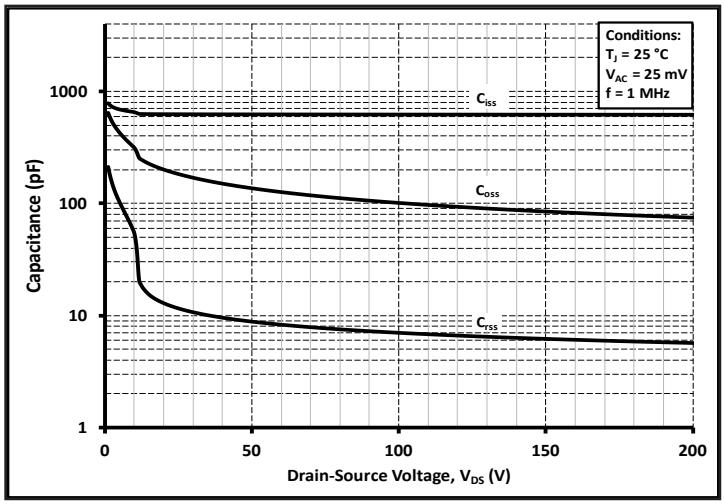


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

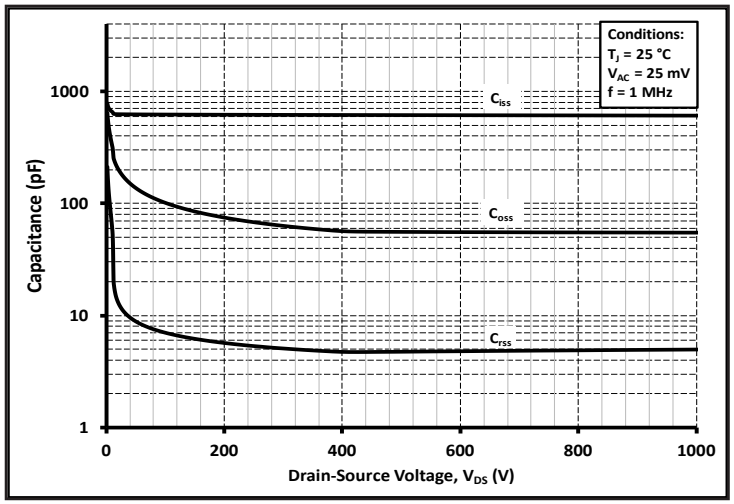


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000V)

Typical Performance

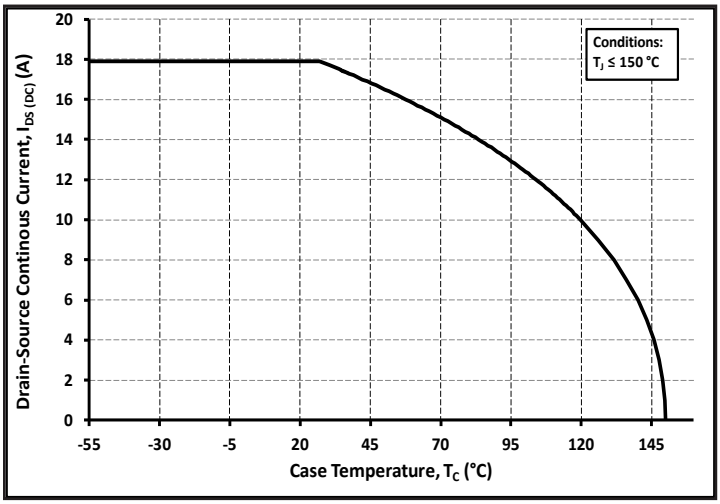


Figure 19. Continuous Drain Current Derating vs. Case Temperature

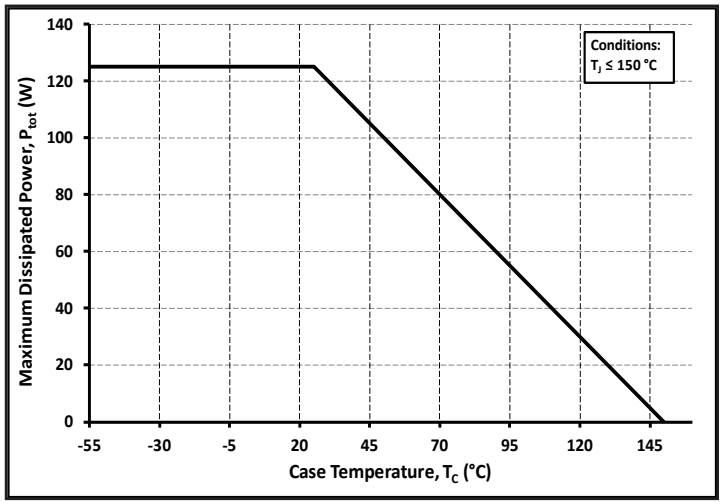


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

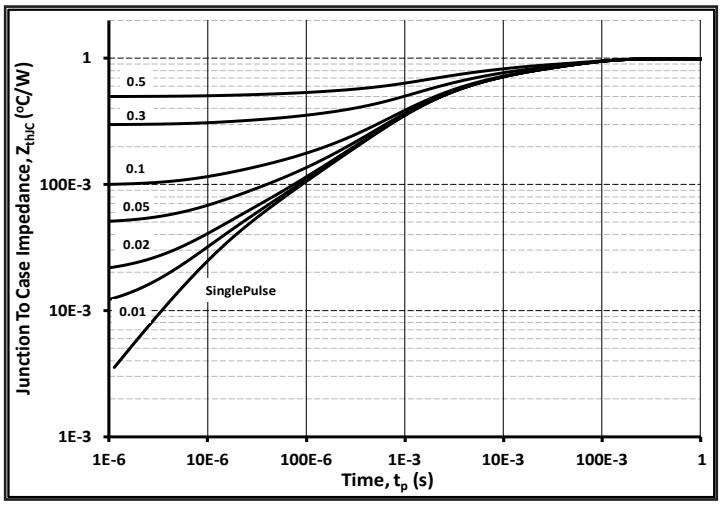


Figure 21. Transient Thermal Impedance (Junction - Case)

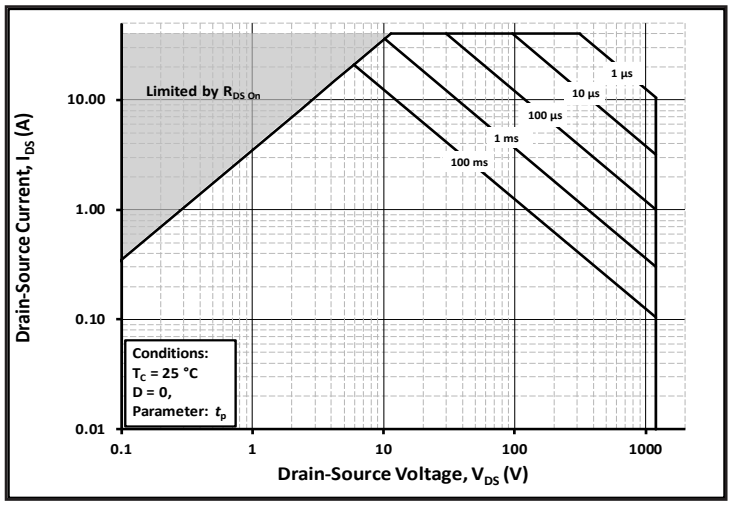


Figure 22. Safe Operating Area

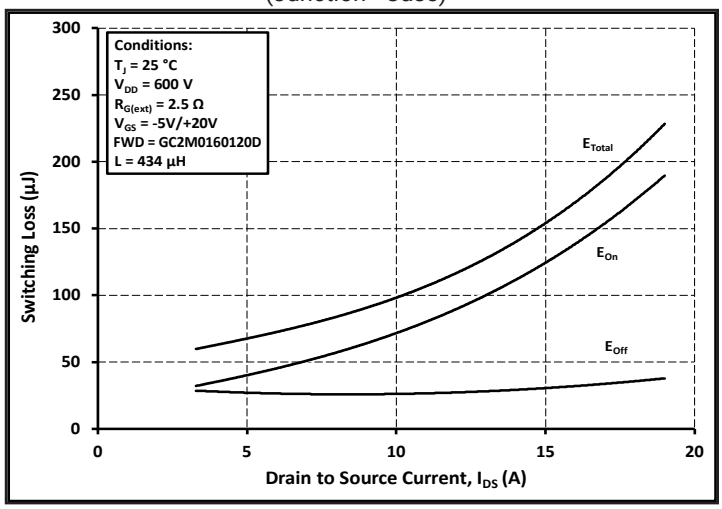


Figure 23. Clamped Inductive Switching Energy vs. Drain Current (V_{DS} = 600 V)

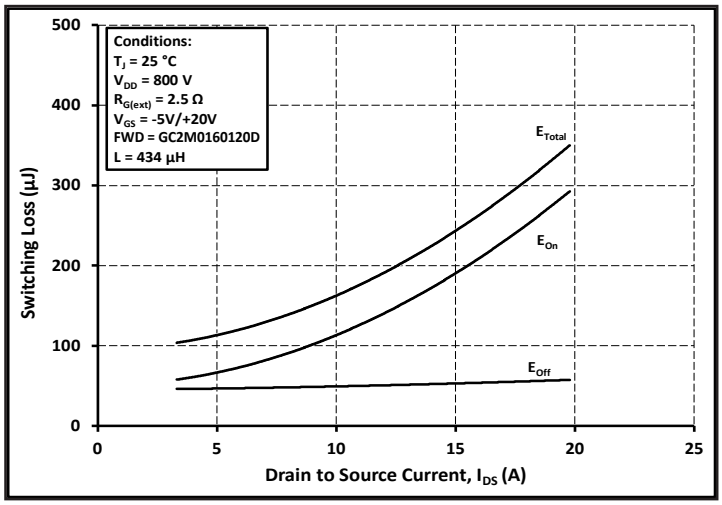


Figure 24. Clamped Inductive Switching Energy vs. Drain Current (V_{DS} = 800 V)

Typical Performance

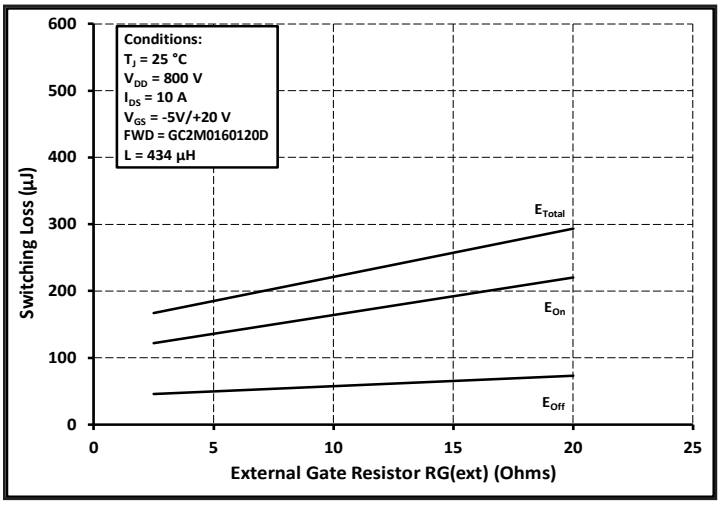


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

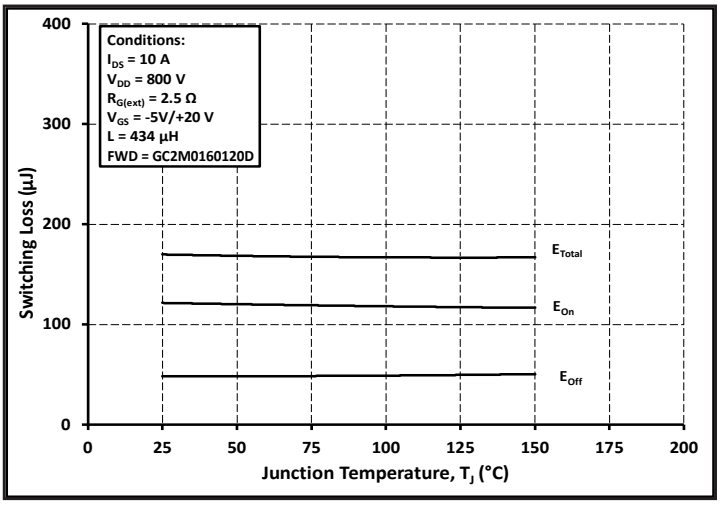


Figure 26. Clamped Inductive Switching Energy vs. Temperature

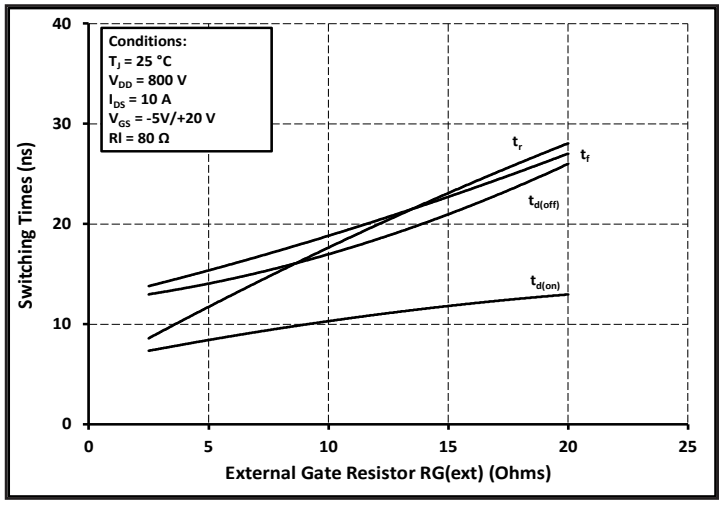


Figure 27. Switching Times vs. $R_{G(ext)}$

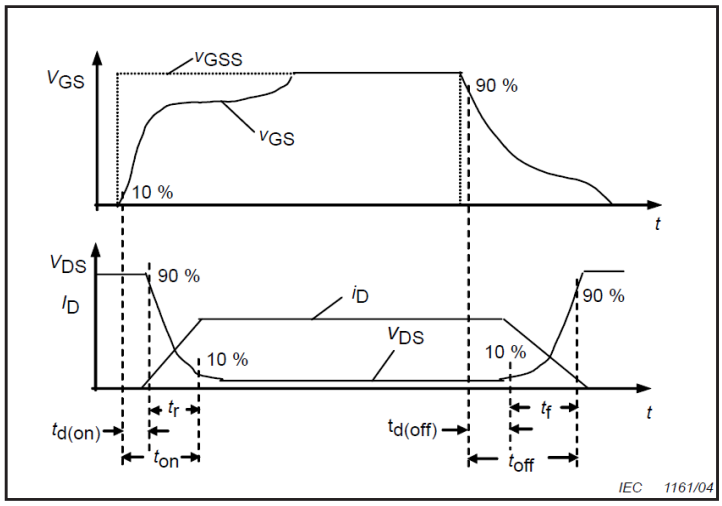


Figure 28. Switching Times Definition

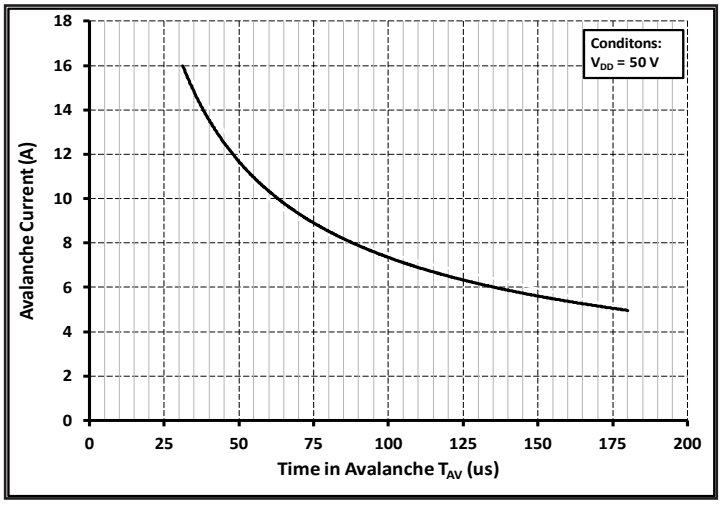


Figure 29. Single Avalanche SOA curve

Test Circuit Schematic

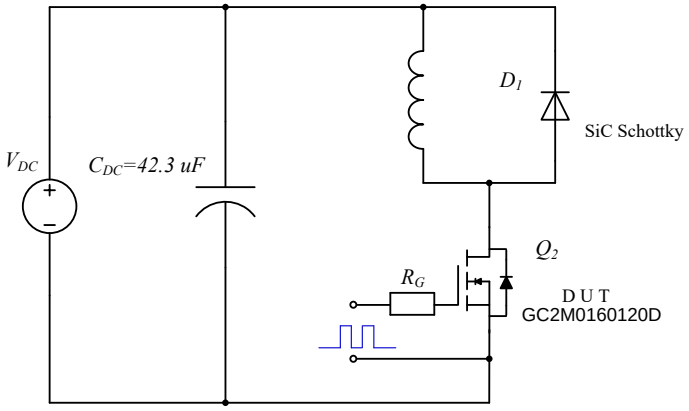


Figure 30. Clamped Inductive Switching Waveform Test Circuit

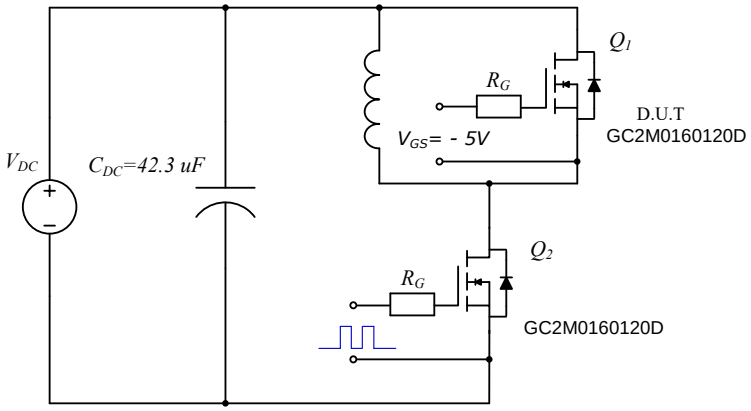


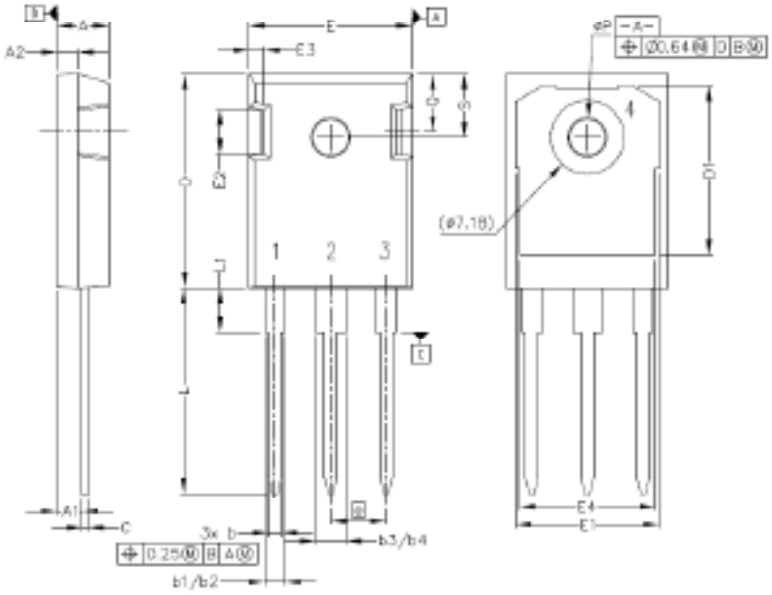
Figure 31. Body Diode Recovery Test Circuit

ESD Ratings

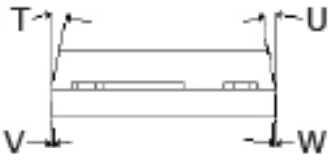
ESD Test	Total Devices Sampled	Resulting Classification
ESD-HBM	All Devices Passed 1000V	2 (>2000V)
ESD-MM	All Devices Passed 400V	C (>400V)
ESD-CDM	All Devices Passed 1000V	IV (>1000V)

Package Dimensions

Package TO-247-3



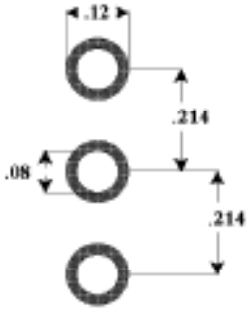
POS	Inches		Millimeters	
	Min	Max	Min	Max
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.042	.052	1.07	1.33
b1	.075	.095	1.91	2.41
b2	.075	.085	1.91	2.16
b3	.113	.133	2.87	3.38
b4	.113	.123	2.87	3.13
c	.022	.027	0.55	0.69
D	.819	.831	20.80	21.10
D1	.640	.695	16.25	17.65
D2	.037	.049	0.95	1.25
E	.620	.635	15.75	16.13
E1	.516	.557	13.10	14.15
E2	.145	.201	3.68	5.10
E3	.039	.075	1.00	1.90
E4	.487	.529	12.38	13.43
e	.214 BSC		5.44 BSC	
N	3		3	
L	.780	.800	19.81	20.32
L1	.161	.173	4.10	4.40
øP	.138	.144	3.51	3.65
Q	.216	.236	5.49	6.00
S	.238	.248	6.04	6.30
T	9°	11°	9°	11°
U	9°	11°	9°	11°
V	2°	8°	2°	8°
W	2°	8°	2°	8°



Pinout Information:

- Pin 1 = Gate
- Pin 2, 4 = Drain
- Pin 3 = Source

Recommended Solder Pad Layout



TO-247-3

Part Number	Package
GC2M0160120D	TO-247-3

单击下面可查看定价，库存，交付和生命周期等信息

>>SUPSiC(国晶微)